L Number	Hits	Search Text	DB
1	2	(wafer adj interposer) and seal	USPAT
2	36	mems and dmd and seal	USPAT
3	67	mems and dmd and cover	USPAT
4	6	mems and dmd and lid	USPAT
5	36	(mems and dmd and cover) and wafer	USPAT
6	95	257/704.ccls. and wafer	USPAT
7	185	(414/938).CCLS.	USPAT
8	479	(414/940).CCLS.	USPAT
9	0	414/91.ccls. and semiconductor	USPAT
10	296	414/941.ccls. and semiconductor	USPAT
12	160	414/938.ccls. and semiconductor	USPAT
13	0	414/938.ccls. and semiconductor and grid	USPAT
14	0	414/938.ccls. and semiconductor and grid	USPAT
15	6	414/940.ccls. and semiconductor and grid	USPAT
16	69	414/940.ccls. and semiconductor and window	USPAT
11	432	414/940.ccls. and semiconductor	USPAT
17	560	257/$.ccls. and (wafer adj carrier)	USPAT
18	5	(257/$.ccls. and (wafer adj carrier)) and interposer	USPAT
19	68	(257/$.ccls. and (wafer adj carrier)) and window	USPAT
21	107	mems and dmd and cover	US-PGPUB; EPO; JPO
20	49	mems and dmd and seal	US-PGPUB; EPO; JPO
22	4	(wafer adj interposer) and seal	US-PGPUB; EPO; JPO; DERWENT